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BT151X-650C

SCR

16 March 2014

Product data sheet

1. General description

Planar passivated Silicon Controlled Rectifier (SCR) in a SOT186A (TO-220F) "full pack" plastic package intended for use in applications requiring high bidirectional blocking voltage capability and high thermal cycling performance.

2. Features and benefits

- High bidirectional blocking voltage capability
- High thermal cycling performance
- Isolated mounting base package
- Planar passivated for voltage ruggedness and reliability

3. Applications

- Capacitive Discharge Ignition (CDI)
- Crowbar protection
- Inrush protection
- Motor control
- Voltage regulation

4. Quick reference data

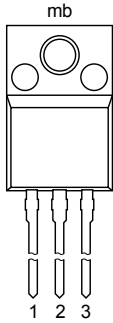

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	-	650	V
V_{RRM}	repetitive peak reverse voltage		-	-	650	V
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 10\text{ ms}$; Fig. 4 ; Fig. 5	-	-	100	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_h \leq 69\text{ °C}$; Fig. 1 ; Fig. 2 ; Fig. 3	-	-	12	A
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25\text{ °C}$; Fig. 7	-	2	15	mA



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 <p>TO-220F (SOT186A)</p>	
2	A	anode		
3	G	gate		
mb	n.c.	mounting base; isolated		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BT151X-650C	TO-220F	plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 "full pack"	SOT186A

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	650	V
V_{RRM}	repetitive peak reverse voltage		-	650	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_h \leq 69^\circ\text{C}$	-	7.5	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_h \leq 69^\circ\text{C}$; Fig. 1; Fig. 2; Fig. 3	-	12	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(\text{init})} = 25^\circ\text{C}$; $t_p = 10\text{ ms}$; Fig. 4; Fig. 5	-	100	A
		half sine wave; $T_{j(\text{init})} = 25^\circ\text{C}$; $t_p = 8.3\text{ ms}$	-	110	A
I^2t	I^2t for fusing	$t_p = 10\text{ ms}$; SIN	-	50	A^2s
di_T/dt	rate of rise of on-state current	$I_T = 20\text{ A}$; $I_G = 50\text{ mA}$; $dI_G/dt = 50\text{ mA}/\mu\text{s}$	-	50	$\text{A}/\mu\text{s}$
I_{GM}	peak gate current		-	2	A

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Symbol	Parameter	Conditions	Min	Max	Unit
V_{RGM}	peak reverse gate voltage		-	5	V
P_{GM}	peak gate power		-	5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	0.5	W
T_{stg}	storage temperature		-40	150	°C
T_j	junction temperature		-	125	°C

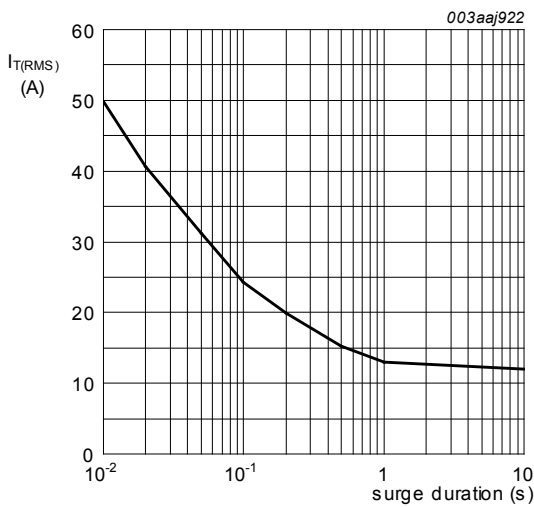


Fig. 1. RMS on-state current as a function of surge duration; maximum values

$f = 50 \text{ Hz}; T_h = 69^\circ\text{C}$

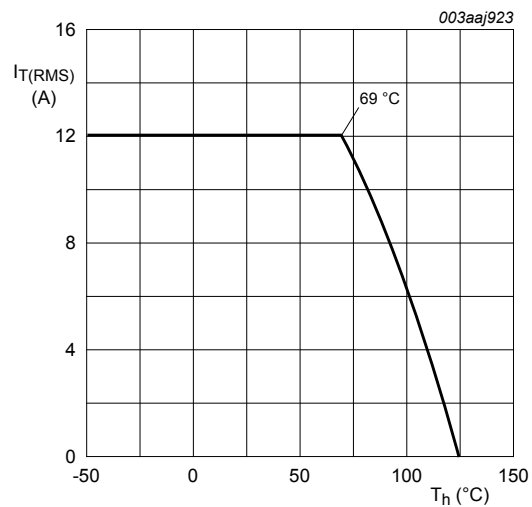


Fig. 2. RMS on-state current as a function of heatsink temperature; maximum values

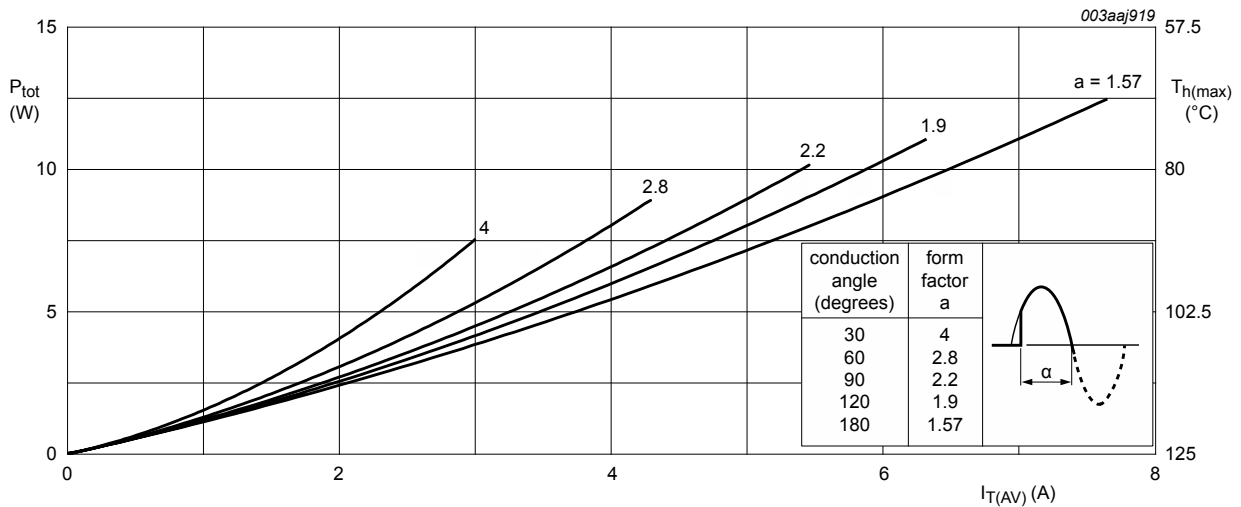


Fig. 3. Total power dissipation as a function of average on-state current; maximum values

$\alpha = \text{conduction angle}$ $a = \text{form factor} = I_{T(RMS)} / I_{T(AV)}$

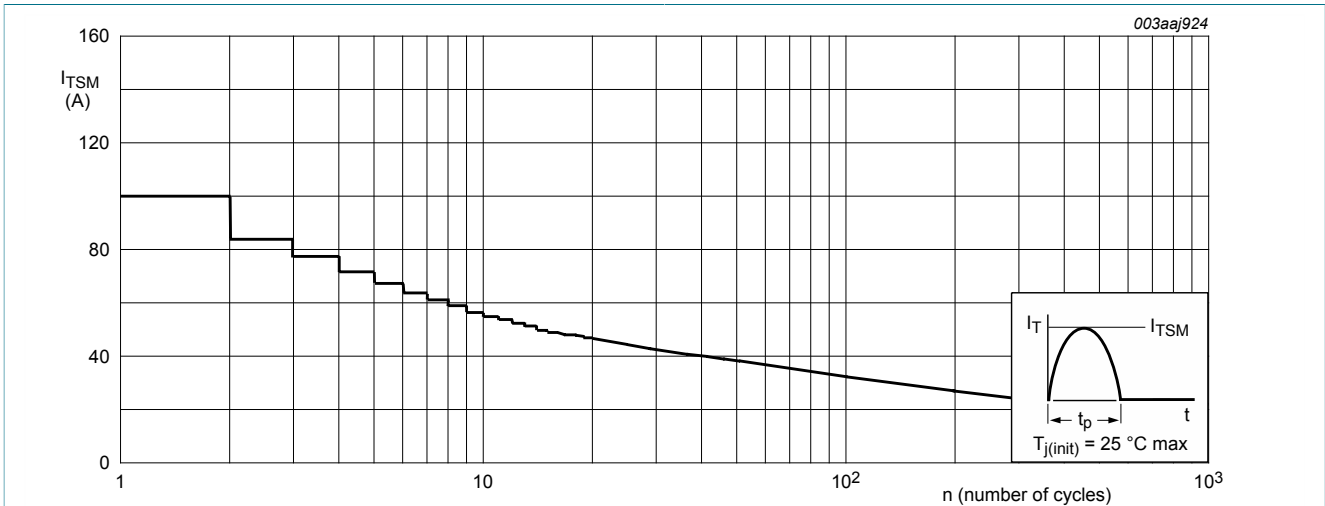


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

f = 50 Hz

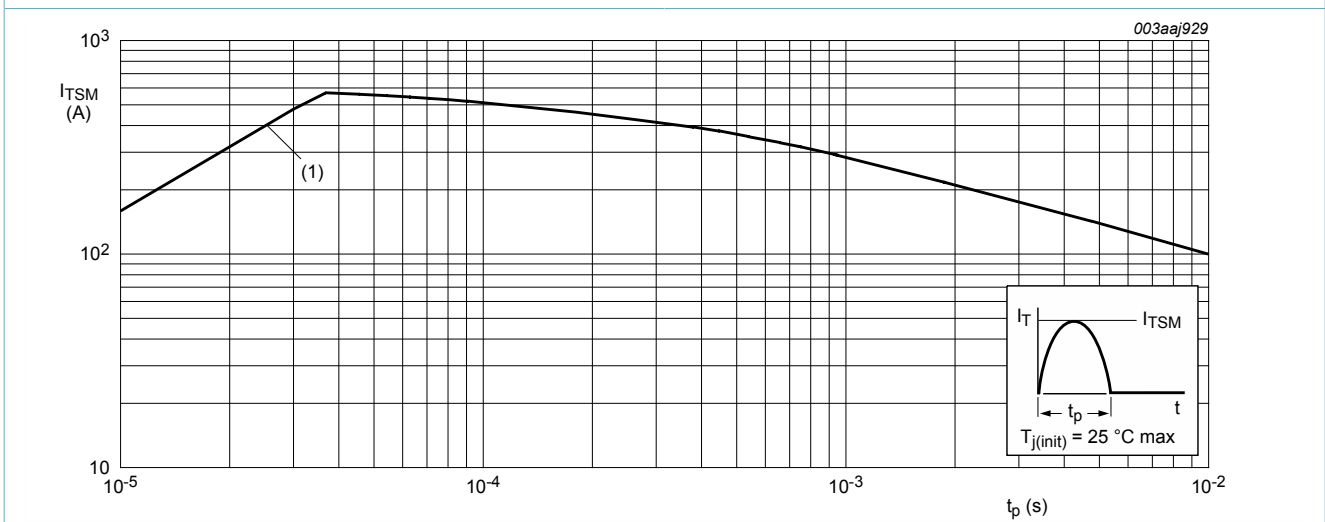


Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values

t_p ≤ 10 ms; (1) dI_T/dt limit

8. Thermal characteristics

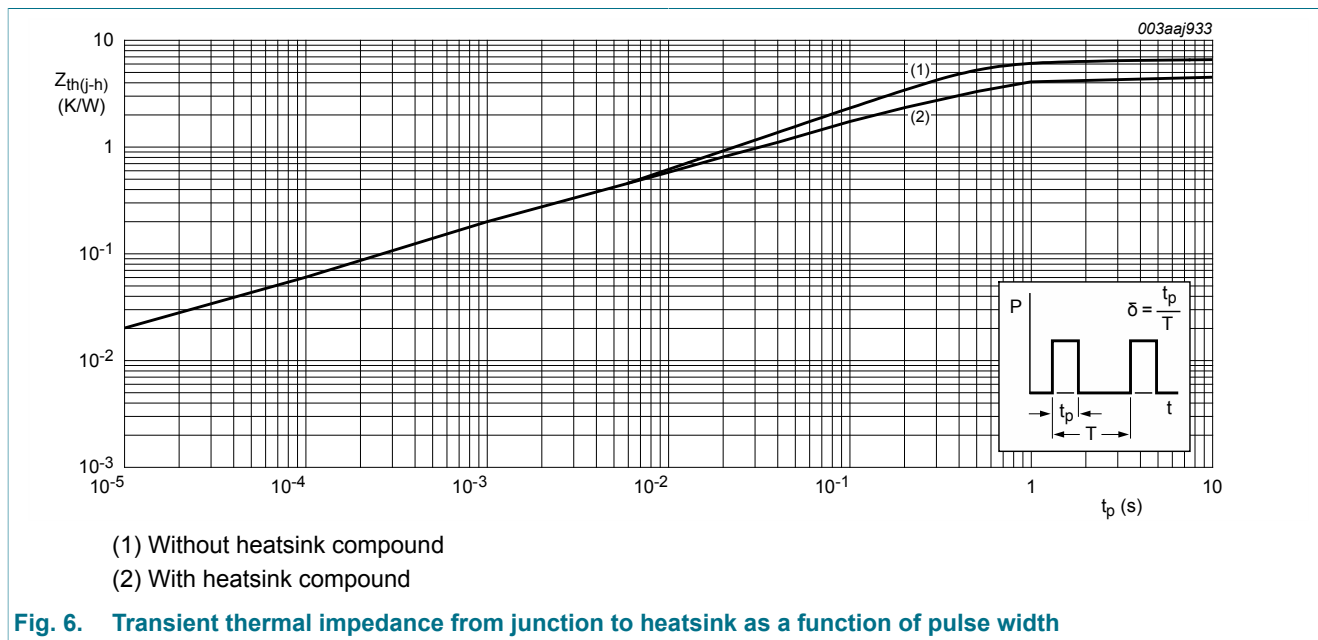
Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R _{th(j-h)}	thermal resistance from junction to heatsink	with heatsink compound; Fig. 6	-	-	4.5	K/W
		without heatsink compound; Fig. 6	-	-	6.5	K/W
R _{th(j-a)}	thermal resistance from junction to ambient	in free air	-	55	-	K/W

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9. Isolation characteristics

Table 6. Isolation characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{isol(RMS)}$	RMS isolation voltage	from all terminals to external heatsink; sinusoidal waveform; clean and dust free; 50 Hz ≤ f ≤ 60 Hz; RH ≤ 65 %; $T_h = 25\text{ °C}$	-	-	2500	V
C_{isol}	isolation capacitance	from anode to external heatsink; f = 1 MHz; $T_h = 25\text{ °C}$	-	10	-	pF

10. Characteristics

Table 7. Characteristics

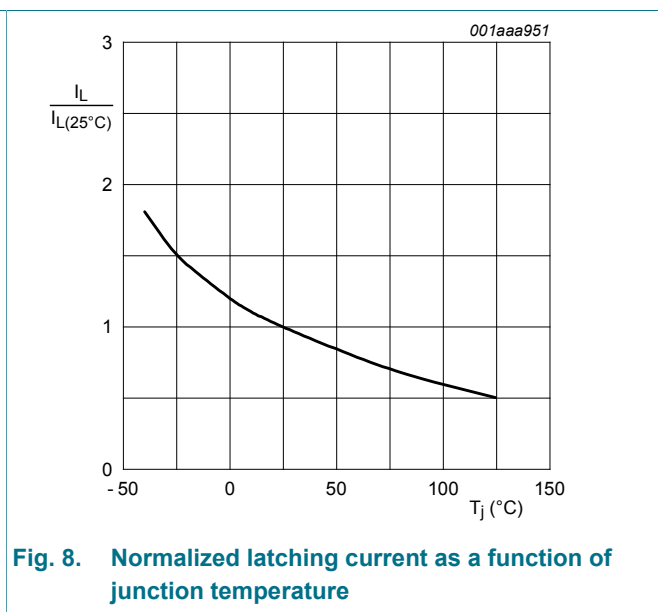
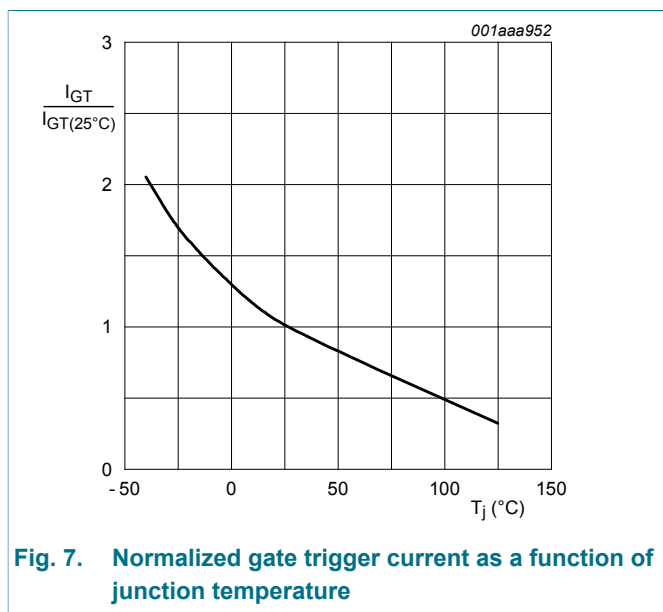
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25\text{ °C}$; Fig. 7	-	2	15	mA
I_L	latching current	$V_D = 12\text{ V}$; $I_G = 0.1\text{ A}$; $T_j = 25\text{ °C}$; Fig. 8	-	10	40	mA
I_H	holding current	$V_D = 12\text{ V}$; $T_j = 25\text{ °C}$; Fig. 9	-	7	20	mA
V_T	on-state voltage	$I_T = 23\text{ A}$; $T_j = 25\text{ °C}$; Fig. 10	-	1.4	1.75	V
V_{GT}	gate trigger voltage	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25\text{ °C}$; Fig. 11	-	0.6	1	V
		$V_D = 650\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 125\text{ °C}$; Fig. 11	0.25	0.4	-	V

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Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_D	off-state current	$V_D = 650\text{ V}; T_j = 125\text{ }^\circ\text{C}$	-	0.1	0.5	mA
I_R	reverse current	$V_R = 650\text{ V}; T_j = 125\text{ }^\circ\text{C}$	-	0.1	0.5	mA
Dynamic characteristics						
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 436\text{ V}; T_j = 125\text{ }^\circ\text{C}; R_{GK} = 100\text{ }\Omega;$ ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; Fig. 12	200	1000	-	V/ μs
		$V_{DM} = 436\text{ V}; T_j = 125\text{ }^\circ\text{C}; (V_{DM} = 67\%$ of V_{DRM}); exponential waveform; gate open circuit; Fig. 12	50	130	-	V/ μs
t_{gt}	gate-controlled turn-on time	$I_{TM} = 40\text{ A}; V_D = 650\text{ V}; I_G = 100\text{ mA};$ $di_G/dt = 5\text{ A}/\mu\text{s}; T_j = 25\text{ }^\circ\text{C}$	-	2	-	μs
t_q	commutated turn-off time	$V_{DM} = 436\text{ V}; T_j = 125\text{ }^\circ\text{C}; I_{TM} = 20\text{ A};$ $V_R = 25\text{ V}; (di_T/dt)_M = 30\text{ A}/\mu\text{s}; dV_D/dt = 50\text{ V}/\mu\text{s};$ $R_{GK} = 100\text{ }\Omega; (V_{DM} = 67\%$ of V_{DRM})	-	70	-	μs



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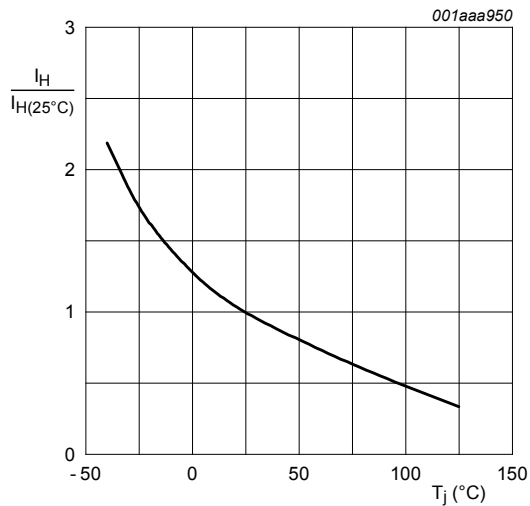
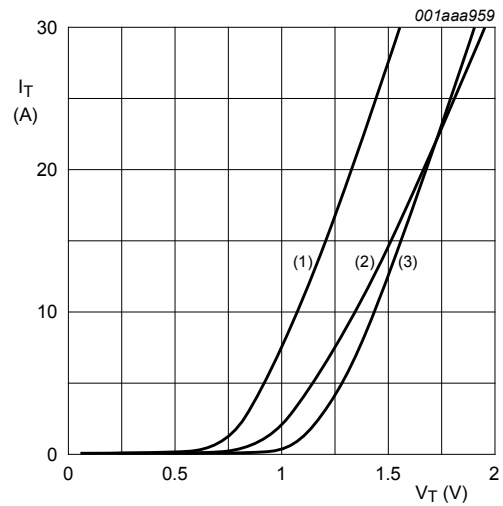


Fig. 9. Normalized holding current as a function of junction temperature



$V_o = 1.06 \text{ V}; R_s = 0.0304 \ \Omega$

(1) $T_j = 125 \text{ }^\circ\text{C}$; typical values

(2) $T_j = 125 \text{ }^\circ\text{C}$; maximum values

(3) $T_j = 25 \text{ }^\circ\text{C}$; maximum values

Fig. 10. On-state current as a function of on-state voltage

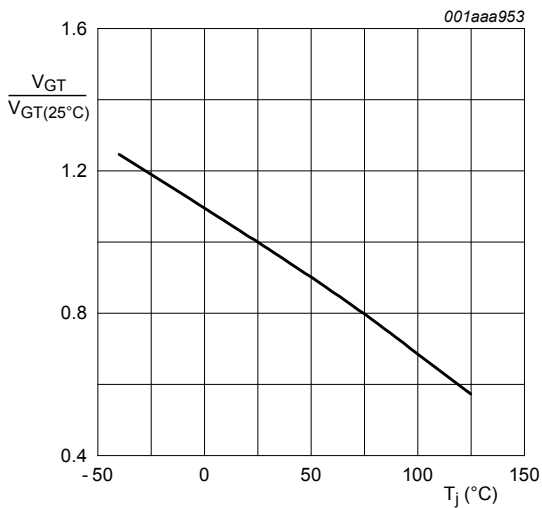
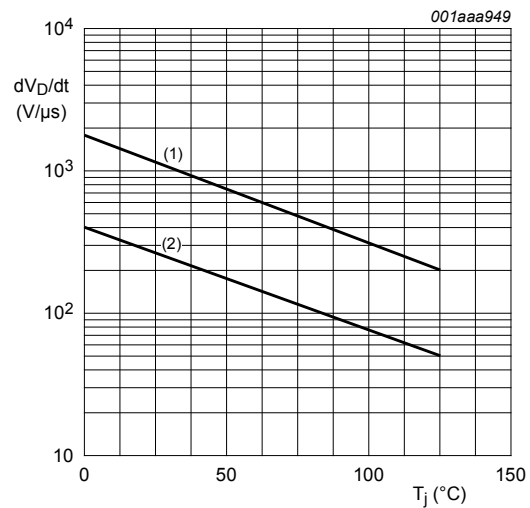


Fig. 11. Normalized gate trigger voltage as a function of junction temperature



(1) $R_{GK} = 100 \ \Omega$;

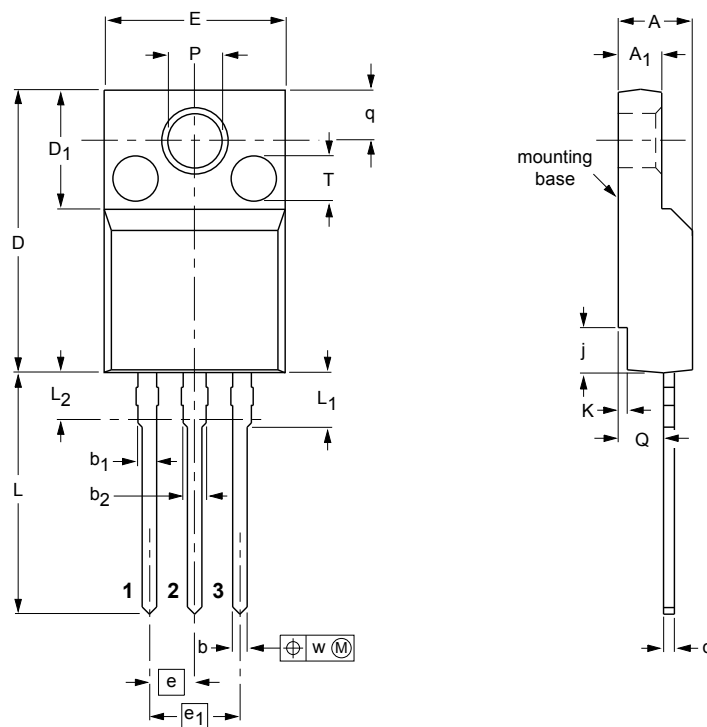
(2) gate open circuit

Fig. 12. Critical rate of rise of off-state voltage as a function of junction temperature; minimum values

11. Package outline

Plastic single-ended package; isolated heatsink mounted;
 1 mounting hole; 3-lead TO-220 'full pack'

SOT186A



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁	b	b ₁	b ₂	c	D	D ₁	E	e	e ₁	j	K	L	L ₁	L ₂ ⁽¹⁾ max.	P	Q	q	T ⁽²⁾	w
mm	4.6 4.0	2.9 2.5	0.9 0.7	1.1 0.9	1.4 1.0	0.7 0.4	15.8 15.2	6.5 6.3	10.3 9.7	2.54	5.08	2.7 1.7	0.6 0.4	14.4 13.5	3.30 2.79	3	3.2 3.0	2.6 2.3	3.0 2.6	2.5	0.4

Notes

- Terminal dimensions within this zone are uncontrolled.
- Both recesses are # 2.5 × 0.8 max. depth

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT186A		3-lead TO-220F			02-04-09 06-02-14

Fig. 13. Package outline TO-220F (SOT186A)

12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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